

PCN

AO-PCN-2025-080-S

Continuous Improvement Process – Laser groove for AS5145

15.09.2025

Dear Customer,

please review this **PCN** and provide your feedback in the **Customer approval form** (at the end of this PCN document) to your ams OSRAM sales partner before **15.10.2025**.

Your prompt reply will help ams OSRAM to assure a smooth and well executed transition. If ams OSRAM does not hear from your side by the due date, we will assume your (if you are a Distributor: and your customer's) full acceptance to this proposed change and its implementation.

ams OSRAM understands the time requirements your organization needs to approve this PCN. However, if you can provide ams OSRAM an estimated date your organization will have finalized this PCN review, ams OSRAM can use this date to plan continued production to secure your order needs during the transition time.

Your attention and response to this matter is highly appreciated.

Please direct your inquiries to your local Sales office.

*) ams OSRAM aligns with the widely recognized JEDEC/ECIA/IPC Joint Standard No. 46, which stipulates:

- Customers should acknowledge receipt of the PCN within 30 days of delivery of the PCN.
- Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.
- After acknowledgement, lack of additional response within the 90 day period constitutes acceptance of the change. If the customer requires additional time to perform sample testing, beyond the 90 day review period, an extension must be negotiated with the supplier.

Subject of change: Continuous Improvement Process – Laser groove for AS5145

Affected products:

177710100	AS5145B-HSST SSOP16 LF T&RDP	Q65114A0597
177710101	AS5145B-HSSM SSOP16 LF T&RDP	Q65114A0598
177710102	AS5145B-HSST SSOP16 LF T&RDP	Q65114A2206
177710103	AS5145B-HSSM SSOP16 LF T&RDP	Q65114A2207
177710124	AS5145B-HSST SSOP16 LF T&RDP	Q65114A0604
177710125	AS5145B-HSSM SSOP16 LF T&RDP	Q65114A2209

Reason for change: Further improvement of existing mechanical sawing methodology is no longer possible. Therefore, we will implement a new additional process which is the application of laser groove.

Description of change:

<u>Current status</u>	<u>New status</u>
Micro-cracks originating from the die chip-out caused by mechanical saw blades during wafer sawing process at Assembly	Application of laser groove process prior mechanical saw process

Time schedule for PCN material: (after implementation):

Final qualification report:	Q1 2026
Samples available:	Q2 2026
Intended Start of delivery:	Q2 2026*

Assessment: There will be no changes in terms of form, fit, function, quality or reliability

Note:

PCN material: Products with implementation of the changes as described in the PCN.

*Depending on demand development, customer qualification plan and customer PCN acceptance

Customer approval form

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Please list product(s) affected in your application(s):

Please check the appropriate box below:

Approval:

We agree with the proposed change and accept start of the shipment upon availability of PCN material

Not relevant:

Change is not relevant for products in use.

Change cannot be accepted:

We have objections:

We request following Information:

We request following Samples:

Expected approval date:

Volume requirements for Pre-PCN material:

Remarks:

Sender:

Company:

Address / Location:

Signature:

Date:

Please return this approval form to your Sales partner.